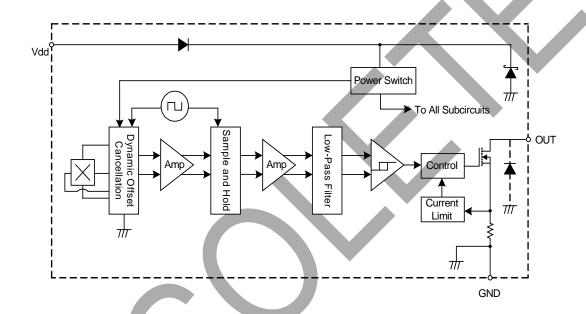


# **Pin Descriptions**

Pin Name	P/I/O	Pin#	Description
Vdd	Р	1	Positive Power Supply
GND	Р	2	Ground
OUT	0	3	Output Pin

# **Functional Block Diagram**



## Absolute Maximum Ratings (T<sub>A</sub> = +25°C)

Symbol	Characteristic	s	Values	Unit
V <sub>DD</sub>	Supply Voltage		30	V
$V_{RDD}$	Reverse Battery Voltage		-30	V
В	Magnetic Flux Density		Unlimited	
Vps	Output OFF Voltage		30	V
I <sub>O(peak)</sub>	Output "On" Current (Peak)		100	mA
T <sub>ST</sub>	Storage Temperature Range		-65 to +150	°C
T <sub>J(MAX)</sub>	Maximum Junction Temperature		+150	°C
Pp	Package Power Dissipation	SIP-3 (Ammo Pack), SIP-3 (Bulk Pack)	550	mW
		SC59	230	mW
θјς	Thermal Resistance Junction to case	SIP-3 (Ammo Pack), SIP-3 (Bulk Pack)	227	°C/W
		SC59	543	°C/W



## **Recommended Operating Conditions**

Symbol	Characteristic	Conditions	Min	Тур.	Max	Unit
$V_{DD}$	Supply Voltage	Operating	3	24	28	٧
T <sub>A</sub>	Operating Ambient Temperature	Operating	-40		+125	°C

# **Electrical Characte**ristics (T<sub>A</sub> = +25°C, V<sub>DD</sub> =24V, Note 4)

Symbol	Characteristic	Test Conditions	Min	Тур.	Max	Unit
V <sub>O(SAT)</sub>	Output Saturation Voltage	lout =20mA, B>Bop	-	300	500	mV
l <sub>OFF</sub>	Output Leakage Current	V <sub>O</sub> =24V, B <bop< td=""><td>-</td><td>&lt; 0.1</td><td>10</td><td>μΑ</td></bop<>	-	< 0.1	10	μΑ
I <sub>DD</sub>	Supply Current	Output Open		4	6	mA
t <sub>R</sub>	Output Rising Time	$R_L = 10k\Omega$ , $C_L = 16pF$	-	340	-	ns
t <sub>F</sub>	Output Falling Time	$R_L = 10k\Omega$ , $C_L = 16pF$	-	20	-	ns
f <sub>C</sub>	Chopping Frequency	-	-	300	-	kHz
Іом	Output Current Limit	B>Bop (Note 5)	50	70	90	mA
tsT	Start-up time of IC	V <sub>DD</sub> >3V, B>Bop (Note 6)	-	47	-	μs

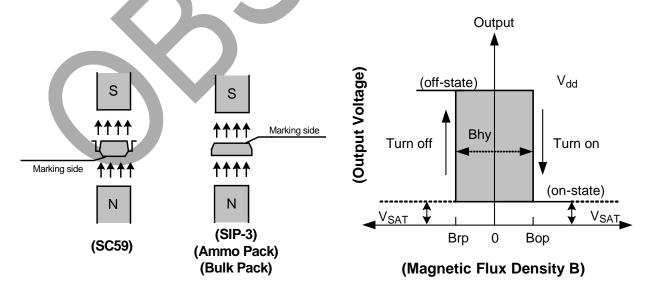
Notes:

- 4. Typical data is at  $T_A$ =+25°C,  $V_{DD}$ =24V and is design information only.
- 5. The device will shut down operating after the output current I<sub>O</sub> is over the output current limit I<sub>OM</sub> for 160µs (typically). The device will re-start up operating after resetting the supply voltage V<sub>DD</sub>.
- 6. In initial power on time, the output state is kept in "High" in this start-up time of IC.

## Magnetic Characteristics (T<sub>A</sub> = +25°C, V<sub>DD</sub> =3V to 28V, Note 7)

				(	1mT=10Gauss)
Symbol	Parameter	Min	Тур.	Max	Unit
Вор	Operate Point	5	30	60	Gauss
Brp	Release Point	-60	-30	-5	Gauss
Bhys	Hysteresis	-	60	-	Gauss

Notes: 7. Magnetic characteristics are for design information, which will vary with supply voltage, operating temperature and after soldering.





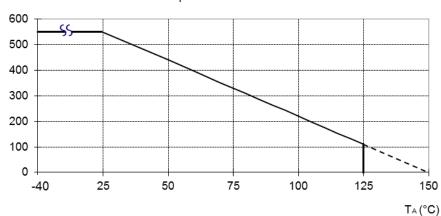
### **Performance Characteristics**

#### (1) SIP-3 (Ammo Pack), SIP-3 (Bulk Pack)

T <sub>A</sub> (°C)	25	50	60	70	80	85	90	95	100
P <sub>D</sub> (mW)	550	440	396	352	308	286	264	242	220
T <sub>A</sub> (°C)	105	110	115	120	125	130	135	140	150
P <sub>D</sub> (mW)	198	176	154	132	110	88	66	44	0

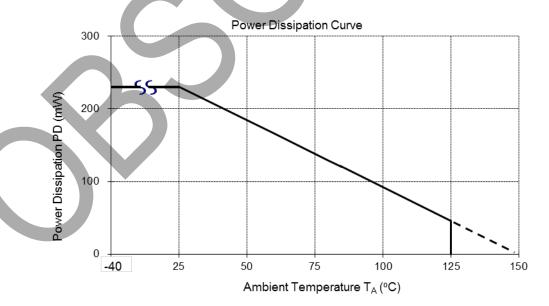


### Power Dissipation Curve



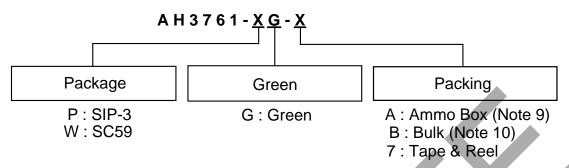
### (2) SC59 (Commonly known as SOT23 in Asia)

T <sub>A</sub> (°C)	25	50	60	70	80	90	100	110	120	125	130	140	150
P <sub>D</sub> (mW)	230	184	166	147	129	110	92	74	55	46	37	18	0





## **Ordering Information**



				Bu	ılk	7" Tape	and Reel	Amm	о Вох
Device	Status (Note 11)	Package Code	Packaging (Note 8)	Quantity	Part Number Suffix	Quantity	Part Number Suffix	Quantity	Part Number Suffix
AH3761-PG-A	EOL	Р	SIP-3(Ammo Pack)	NA	NA	NA	NA	4000/Box	-A
AH3761-PG-B	NRND	Р	SIP-3(Bulk Pack)	1000	-B	NA	NA	NA	NA
AH3761-WG-7	NRND	W	SC59	NA	NA	3000/Tape & Reel	-7	NA	NA

Notes:

- 8. Pad layout as shown on Diodes Incorporated's suggested pad layout document, which can be found on our website at http://www.diodes.com/package-outlines.html.

  9. Ammo Box is for SIP-3 Spread Lead.

  10. Bulk is for SIP-3 Straight Lead.

  11. NRND = Not Recommended for New Design.

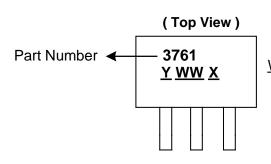
  EOL = End of Life.





### **Marking Information**

(1) Package Type: SIP-3 (Ammo Pack), SIP-3 (Bulk Pack)



Y: Year: 0~9

WW: Week: 01~52, "52" represents

52 and 53 week

X: Internal Code: A~Z: Green

Part Number	Package	Identification Code
AH3761	SIP-3 (Ammo Pack)	3761
AH3761	SIP-3 (Bulk Pack)	3761

(2) Package Type: SC59



XX YWX

XX: Identification code Y: Year 0~9

<u>W</u>: Week: A~Z: 1~26 week;

a~z : 27~52 week; z represents

52 and 53 week X: A~Z: Green

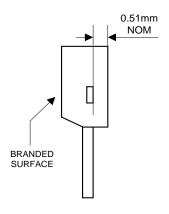
Part Number	Package	Identification Code
AH3761	SC59	P8



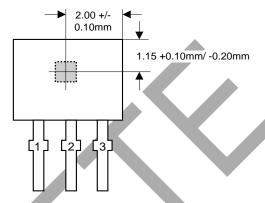
## Package Outline Dimensions (All Dimensions in mm)

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### (1) Package Type: SIP-3 (Bulk Pack)

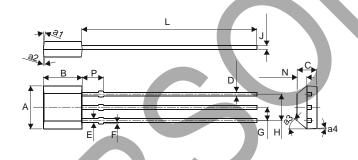


Active Area Depth



**Sensor Location** 

#### **Package Dimension**



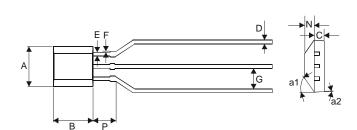
SIP-3								
(1	(Bulk Pack)							
Dim	Min	Max						
Α	3.9	4.3						
a1	5	□ур						
a2	5	□Ту						
a3	45	☐ Ty						
a4	3	□Ту						
В	2.8	3.2						
C	1.40	1.60						
D	0.33	0.432						
Е	0.40	0.508						
F	0	0.2						
G	1.24	1.30						
Н	2.51	2.57						
7	0.35	0.43						
L	14.0	15.0						
N	0.63	0.84						
Р	1.55	-						
All Din	All Dimensions in mm							



# Package Outline Dimensions (Cont.)

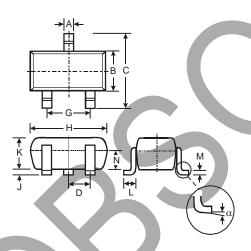
Please see http://www.diodes.com/package-outlines.html for the latest version.

### (2) Package Type: SIP-3 (Ammo Pack)

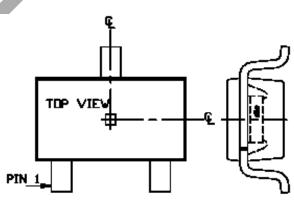


	SIP-3							
(/	(Ammo Pack)							
Dim	Min	Max						
Α	3.9	4.3						
a1	45	☐ Ty						
a2	3	□Ту						
В	2.8	3.2						
С	1.40	1.□0						
	0□35	0.41						
E	0.43	0.48						
F	0	0.2						
G	2.4	2.9						
N	0.63	0.84						
Р	1.55	-						
All Di	mension	s in mm						

### (3) Package Type: SC59



SC59				
Dim	Min	Max	Тур	
Α	0.35	0.50	0.38	
В	1.50	1.70	1.60	
С	2.70	3.00	2.80	
D	-	-	0.95	
G	-	-	1.90	
Н	2.90	3.10	3.00	
J	0.013	0.10	0.05	
K	1.00	1.30	1.10	
L	0.35	0.55	0.40	
M	0.10	0.20	0.15	
N	0.70	0.80	0.75	
	0°	8°	-	
All Dimensions in mm				



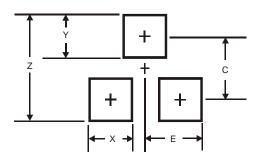
@=Package Center Line



# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### (1) Package Type: SC59



Dimensions	Value (in mm)	
Z	3.4	
Х	0.8	
Υ	1.0	
С	2.4	
E	1.35	



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